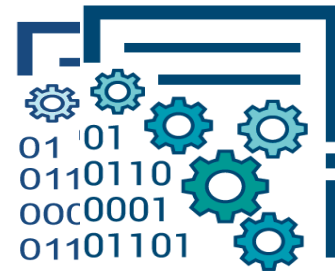
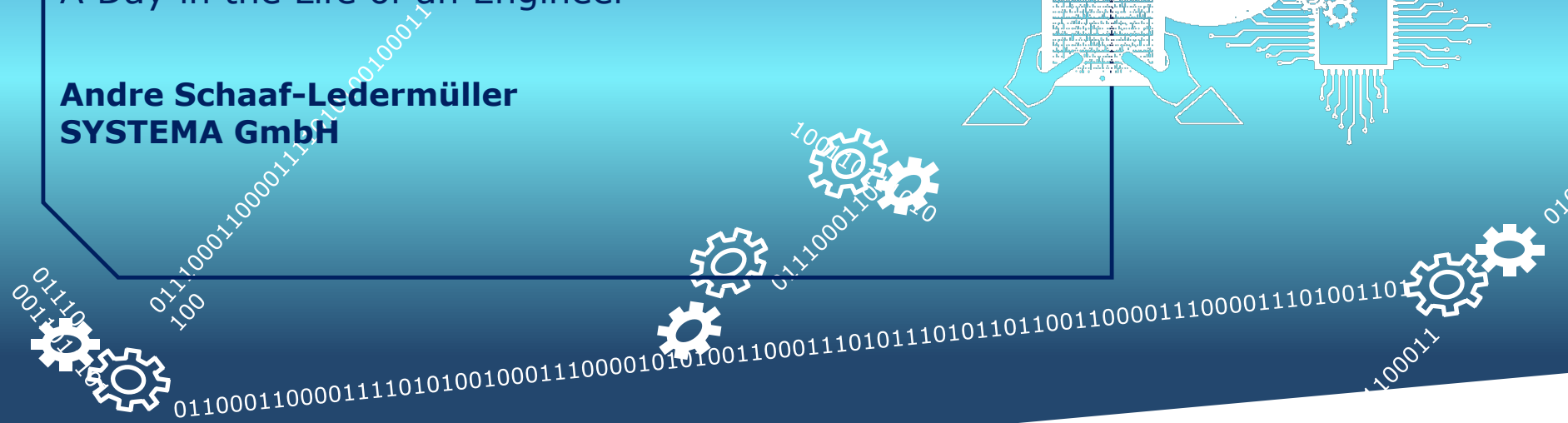
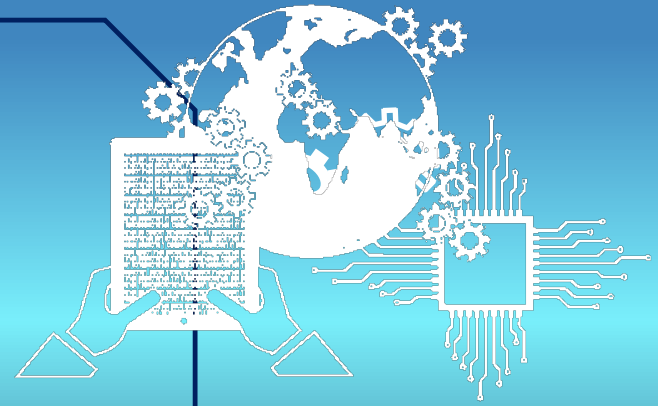


New defect classification methodology with regard to causal modeling, supervised by engineers (SME)

A Day in the Life of an Engineer

Andre Schaaf-Ledermüller
SYSTEMA GmbH



iDev40



ECSEL JU

The project iDev40 is co-funded by the ECSEL Joint Undertaking, grants from Austria, Belgium, Germany and Spain as well as the European Structural and Investment Funds. It is coordinated by Infineon Technologies Austria AG.



Agenda



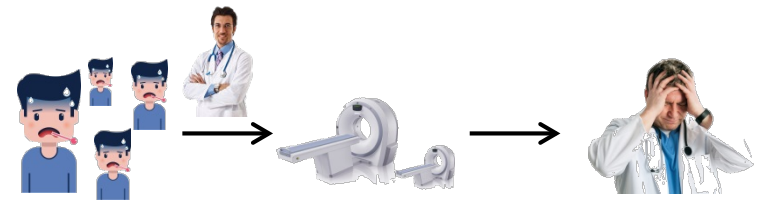
- › Motivation, where does DE (defect engineering) comes from
- › A day in the life of an engineer
- › New kind of defects
- › Causal source / causal model
- › Adaptation of causal model / training
- › AI validation
- › Conclusion / open questions

Example: health care vs. semiconductor

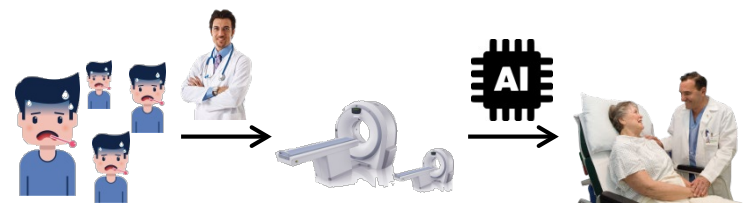
Health Care



1990 - 2000

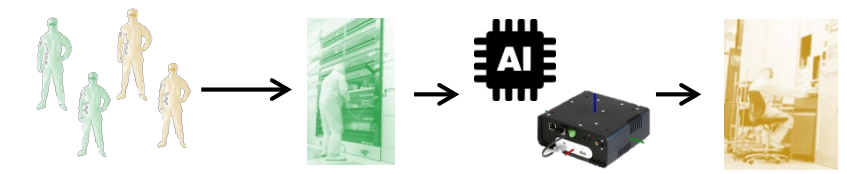
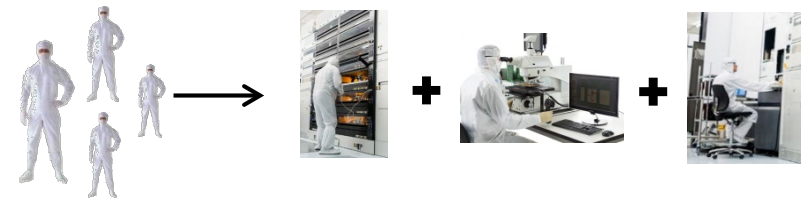


2000 - 2020



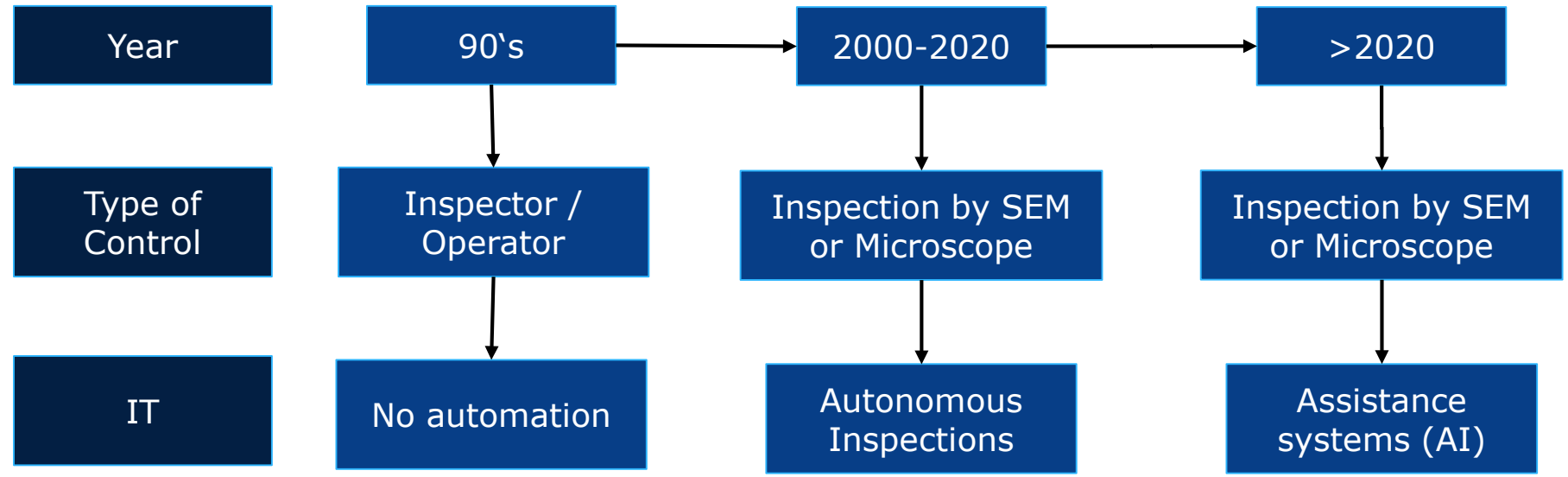
2020 - 2050

Semiconductor





The evolution of DDE automation



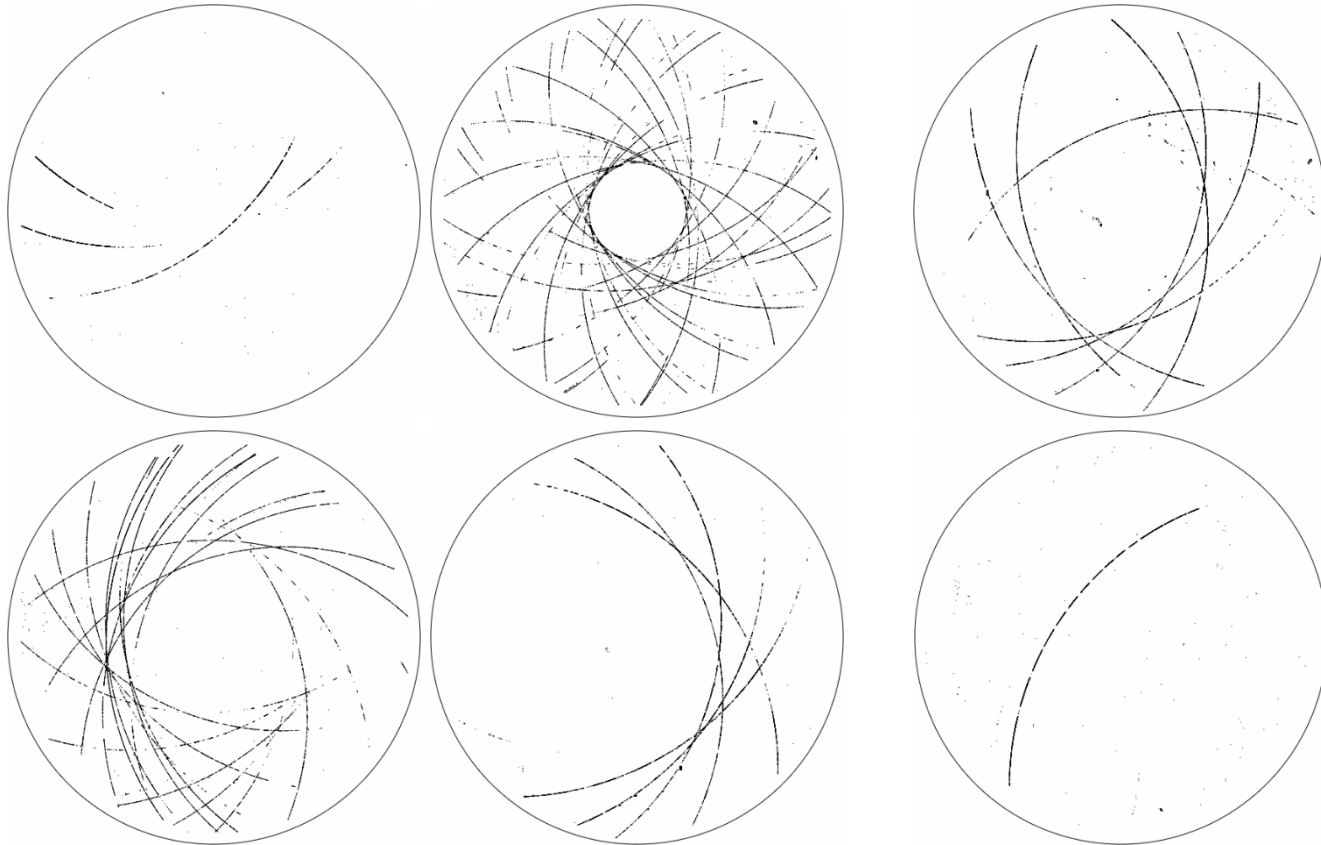


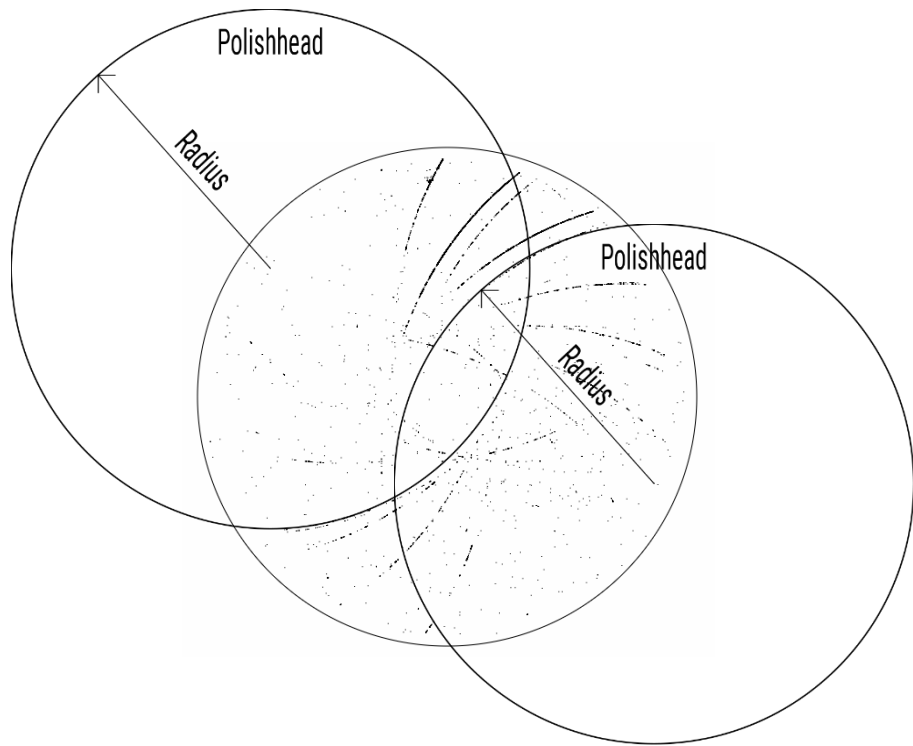
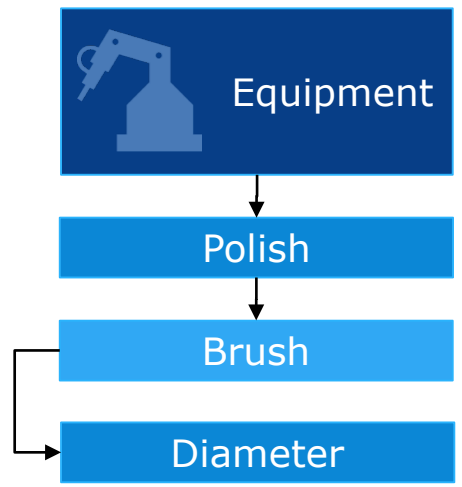
9:00AM – A Normal Day



- Engineer begins work
- Checks Mail
- Receives notification of a problem in production with a polisher tool
- Operator attached a list of wafers
- Engineer lookups polisher tool in a database
- Production operation lookup

9:30AM – Defect Image Analysis





Causal Model

Environment

Causal Origin

Causal Type

Causal Property

Route

Equipment

Operator

Material

Polish

Etching

Cleaning

...

Brush

Slurry

Particle

...

Diameter

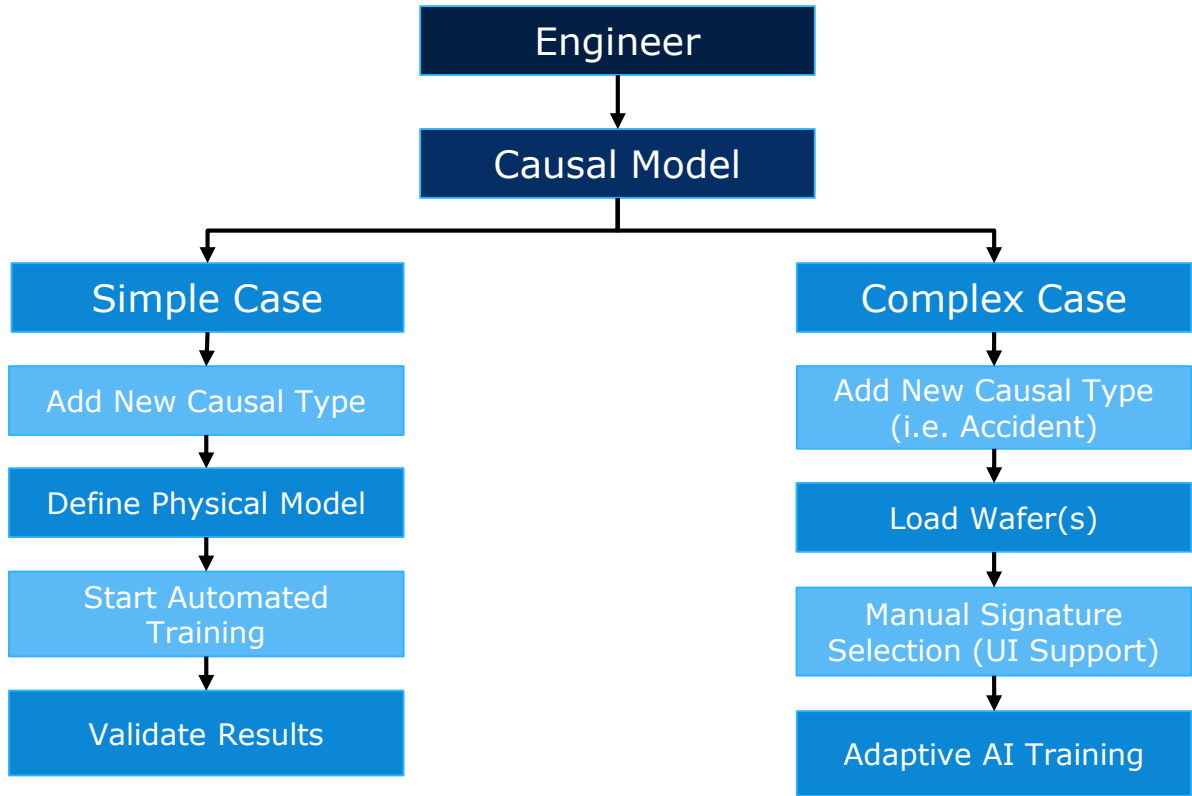
Recipe

Maintenance

...

- Engineer understands the problem
- Knowledge of which operation / range causes the signatures
- Opens the cause modeling / training suite
- Lookups existing causal model types
- Starts creation of new causal model type
 - Polisher tool with 300mm diameter

Training Modes



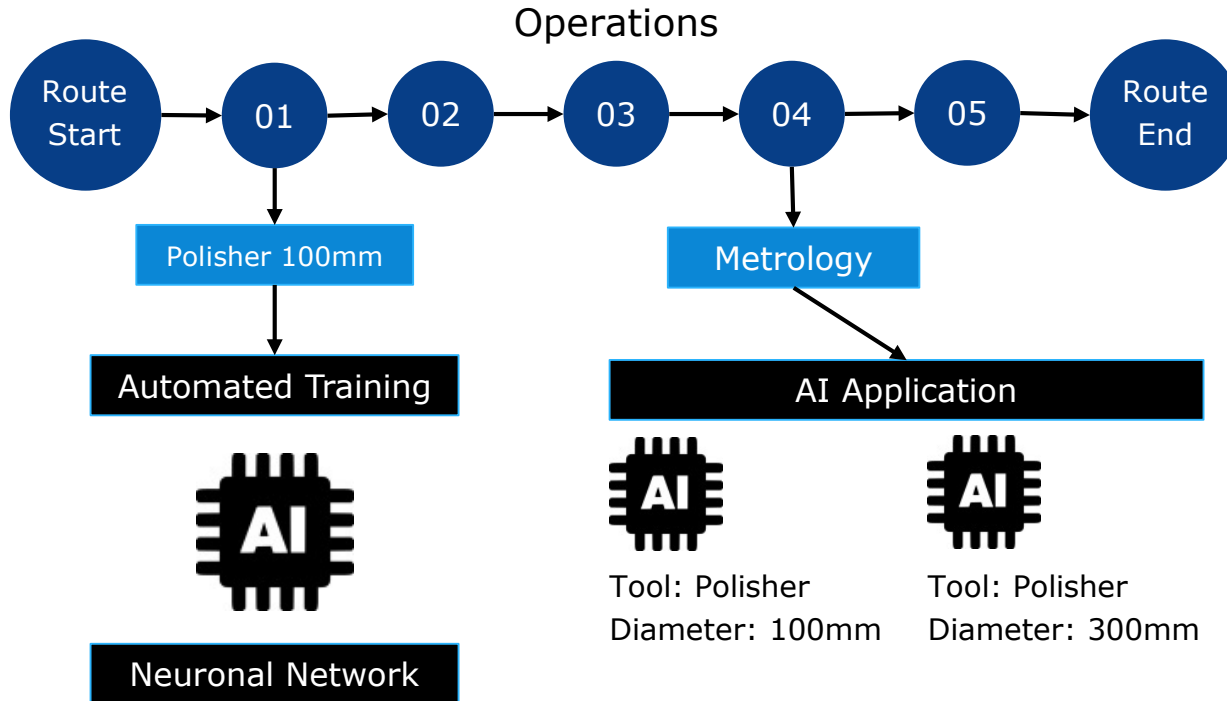


1:00PM Causal Model Adapted



- Engineer adapted the causal model
- Created a new causal model type for polish tool 300mm diameter
- Defined parameters for the training environment
- Assigned the new causal model type to the specific operation
- Started the training phase

Production Route



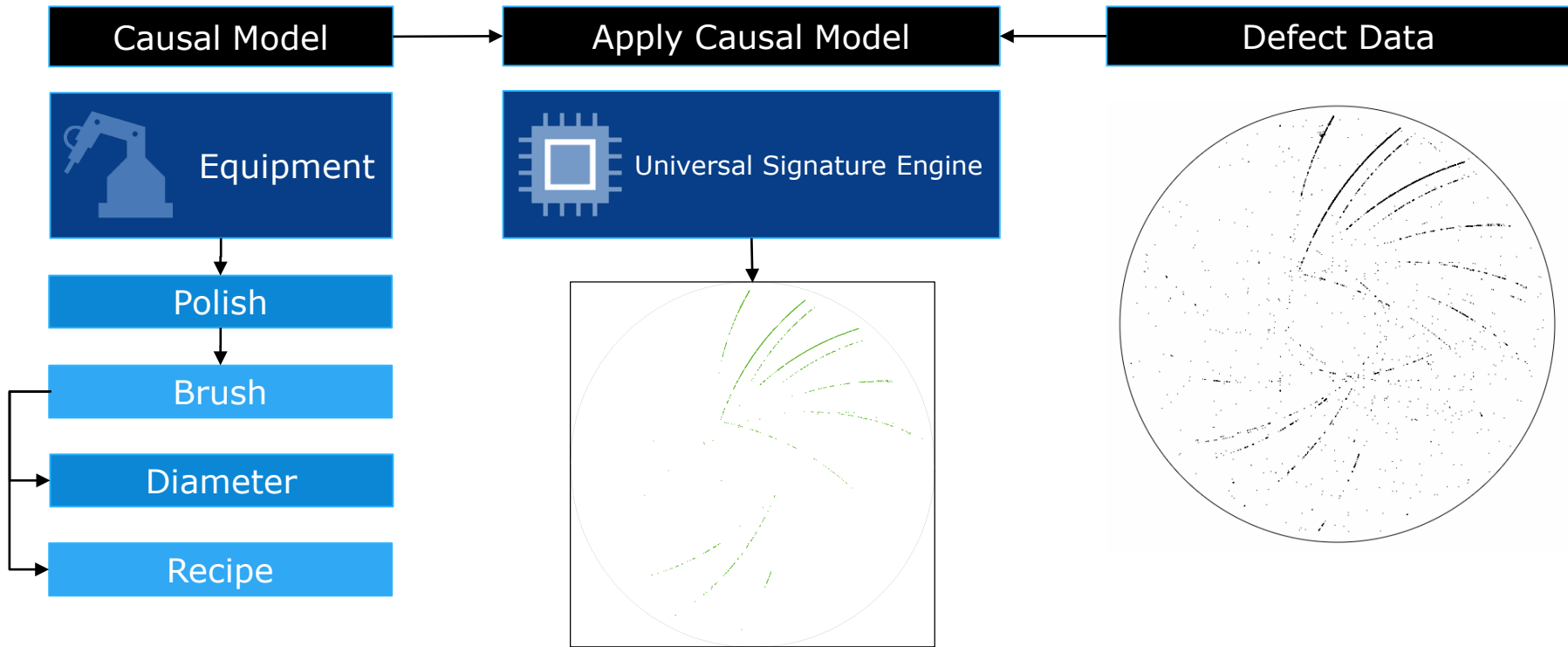


3:00PM AI Training finished



- The AI toolkit reports that the training is finished
- Engineer loads validation data (100s / 1000s of wafers)
- Start of validation / QA process
- AI is tested against the mass data before production ready

Causal Model Application



- The AI found 85% of signatures
- Engineer adding missing signatures by manual signature selection within modelling toolkit
- Adaptive AI training with the expert knowledge of the engineer
- Starting AI validation

- AI now has 90% accuracy rate
- Accuracy rate is defined by QM
- AI is now certified for production
- AI is assigned to the specific metrology operation where the signatures occurred
- AI is moved to production and supports the signature detection

- Engineers' expertise is still required
- As humans are producing errors so can AI system
- AI system is meant to support the production process
- Easy to use user interfaces
- Elimination of complex algorithms with loads of parameters
- Elimination of undefined behaviour of statistical algorithms
- Faster and error reduced detection setup

- Back side scans with large defect densities can cause fuzzy signature recognition
- Solution: Application of density reduction with specialized reduction algorithm
 - -> Loss of information
 - -> Only parts of signatures can be detected

Thank You!

